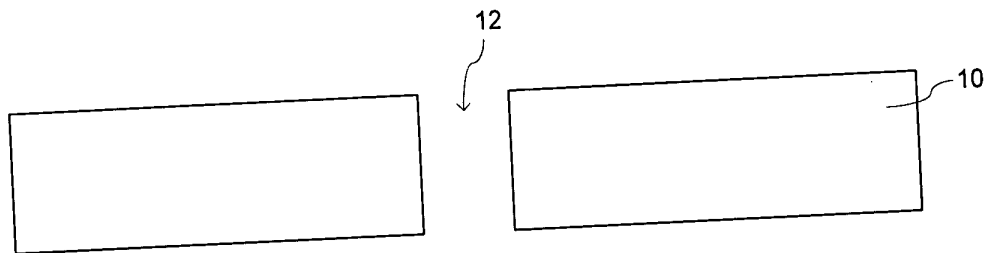
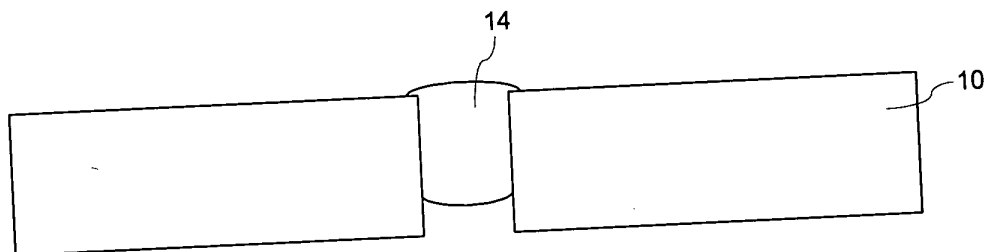


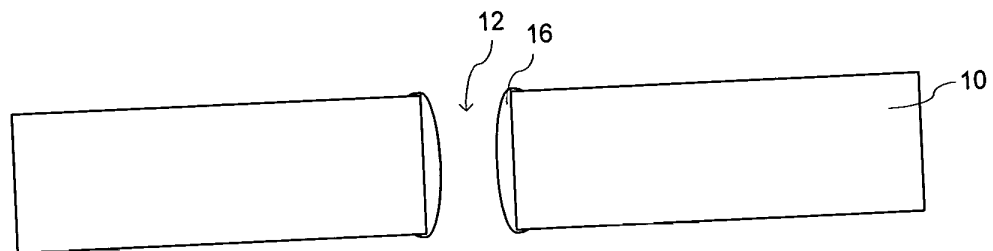
**Figure 1a**



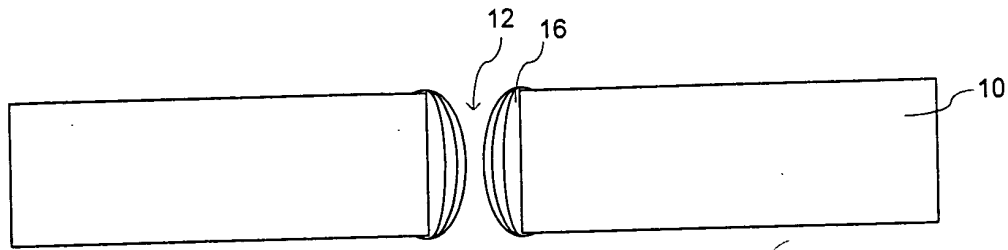
**Figure 1b**



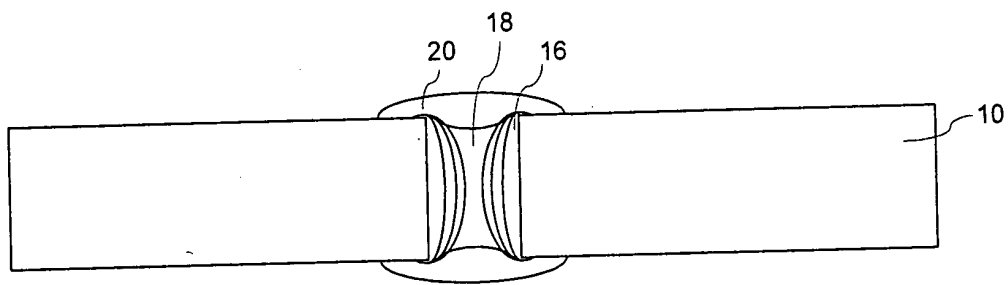
**Figure 1c**



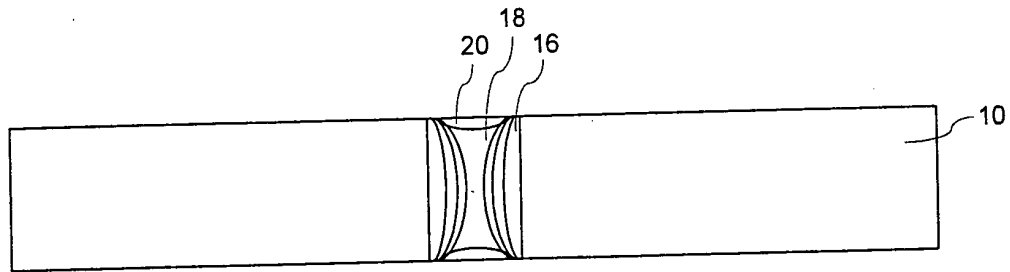
**Figure 1d**



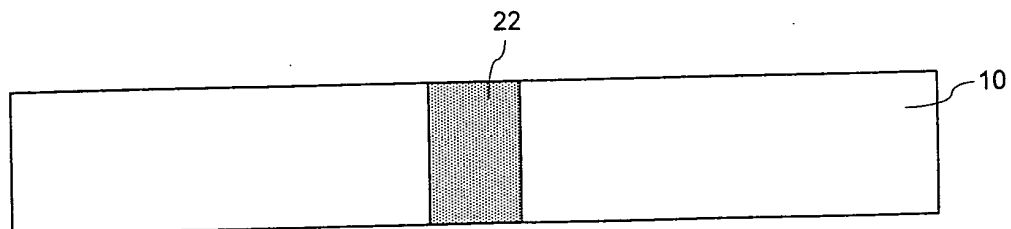
**Figure 1e**



**Figure 1f**



**Figure 1g**



**Figure 1h**

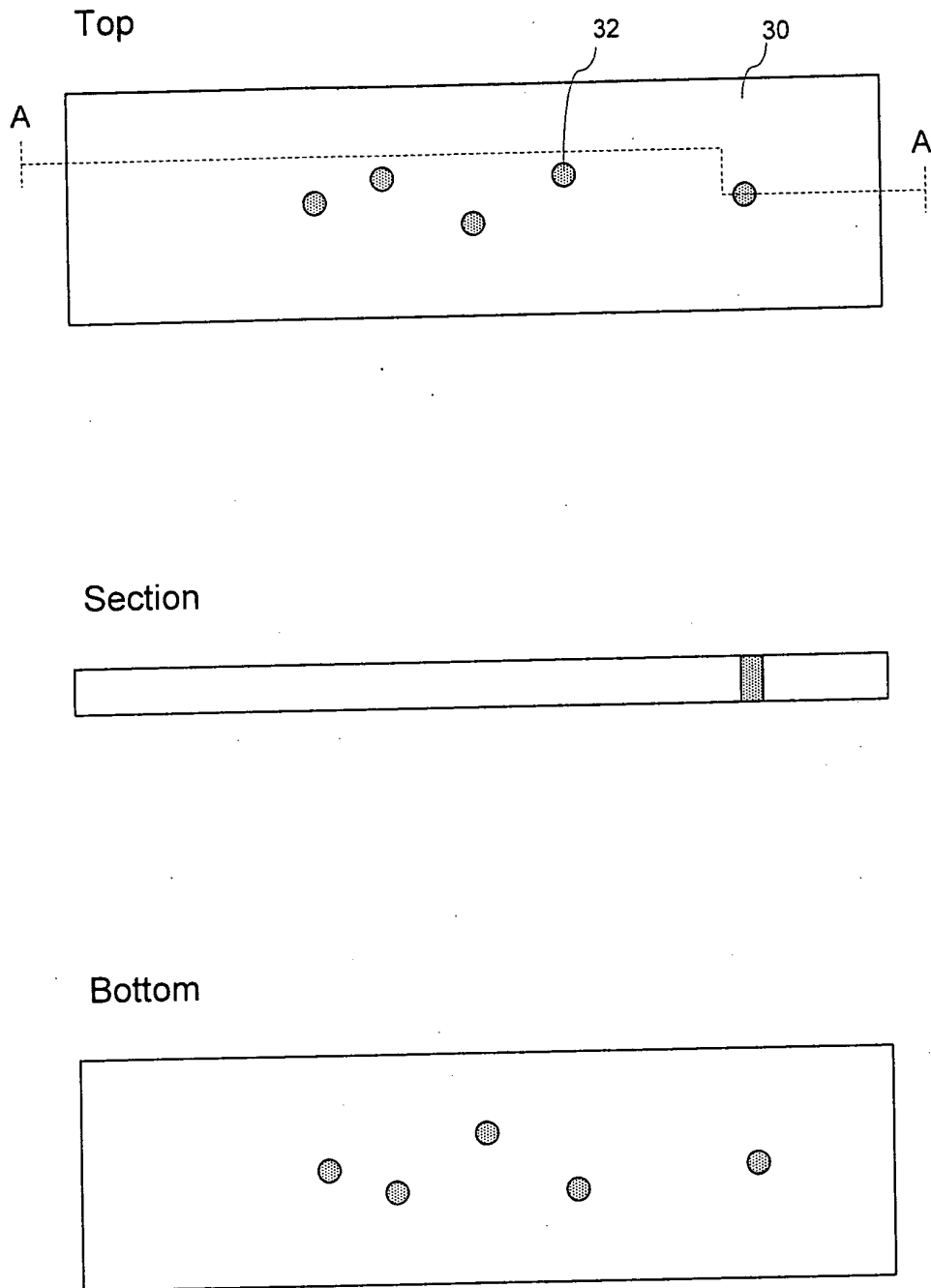


Figure 2a

HIGH RELIABILITY MULTILAYER CIRCUIT  
SUBSTRATES AND METHODS FOR THEIR  
FORMATION

Inventors: Rajiv Shah et al.

Attorney: Ted R. Rittmaster - 047711-0319

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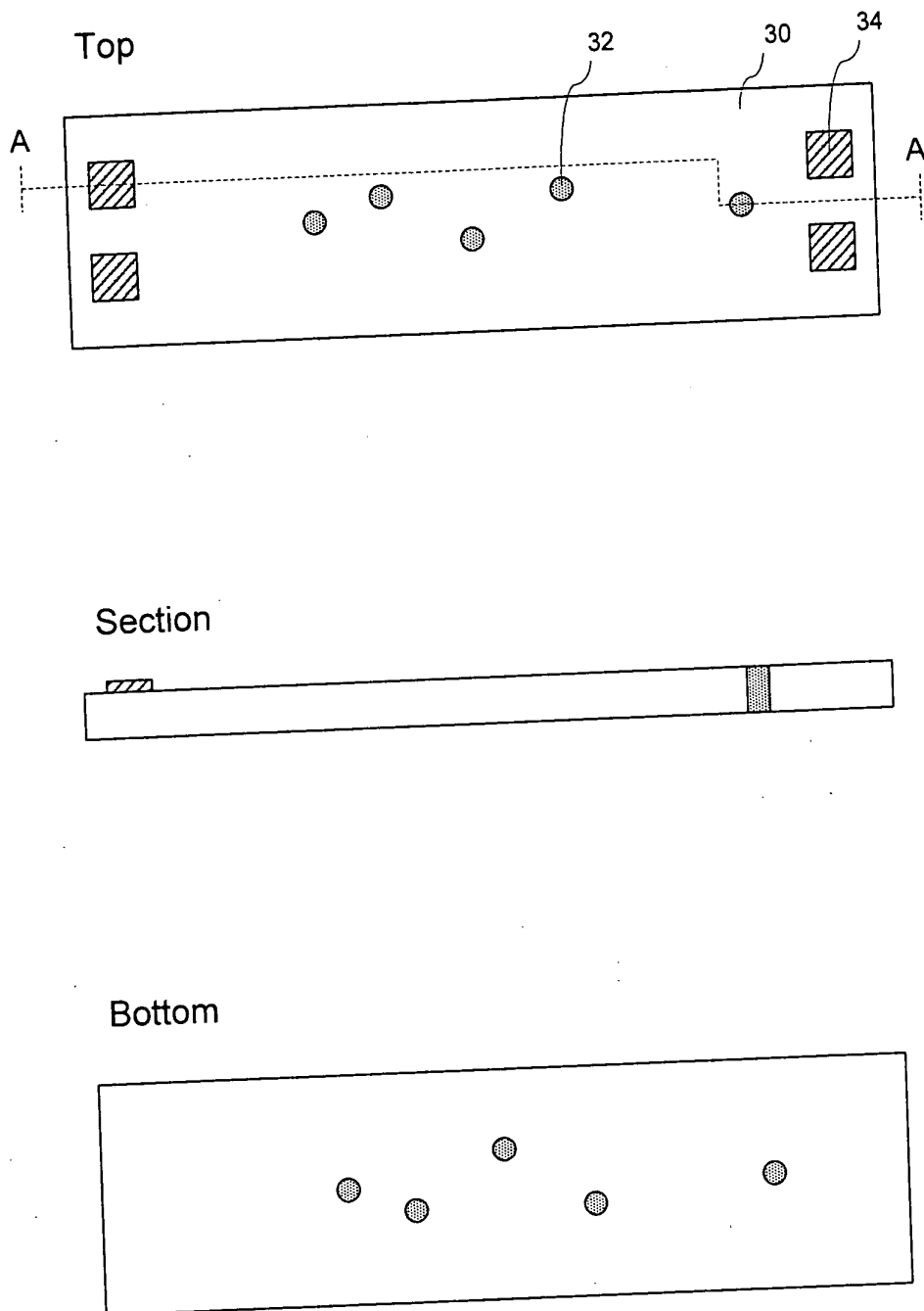


Figure 2b

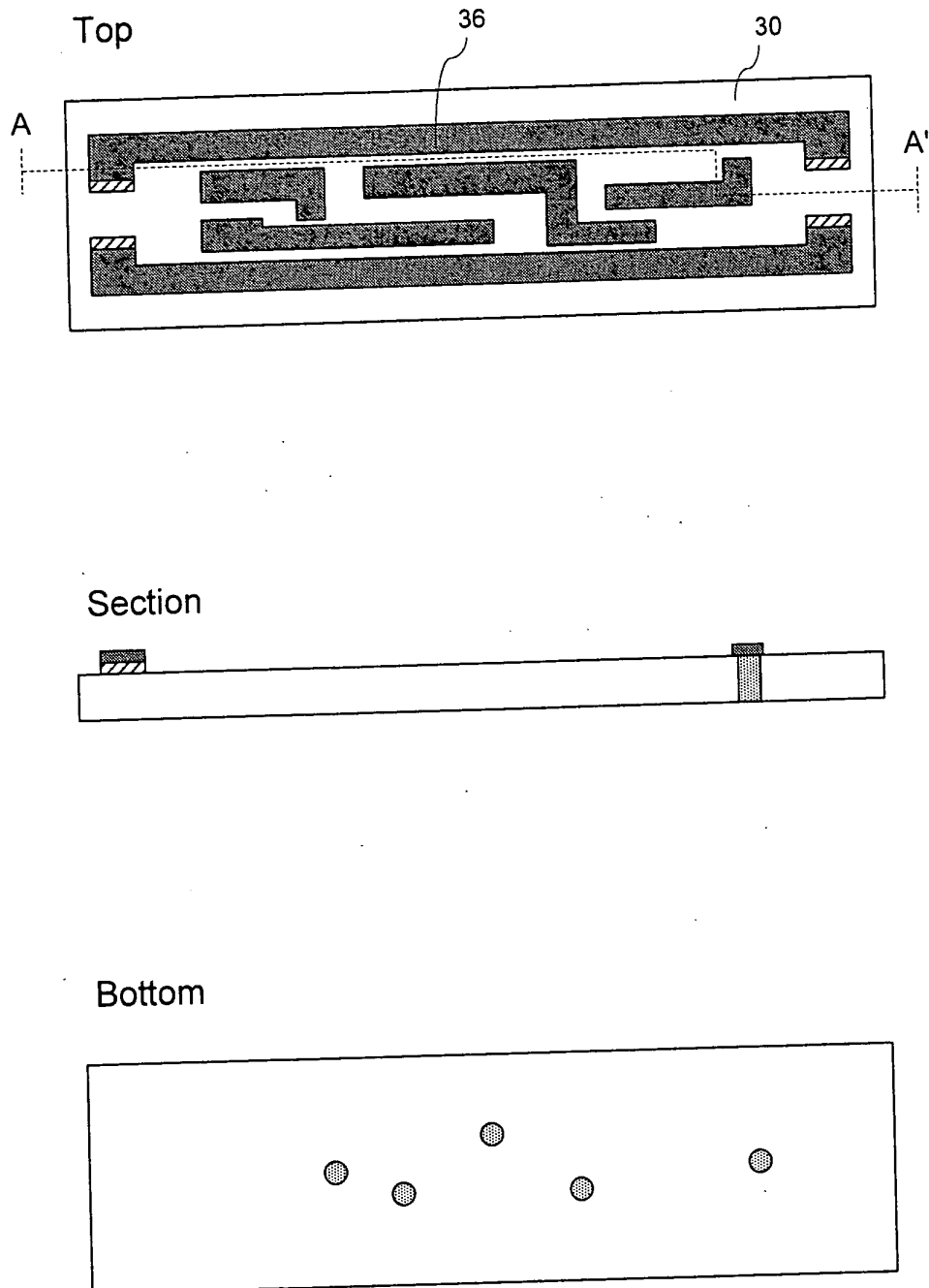


Figure 2c

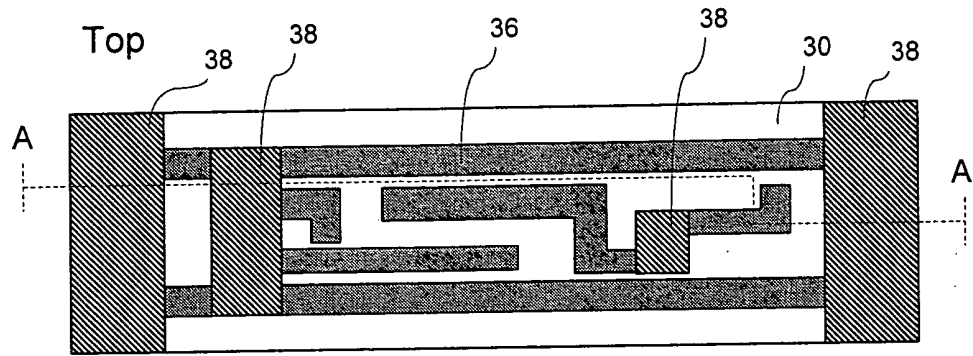
HIGH RELIABILITY MULTILAYER CIRCUIT  
SUBSTRATES AND METHODS FOR THEIR  
FORMATION

Inventors: Rajiv Shah et al.

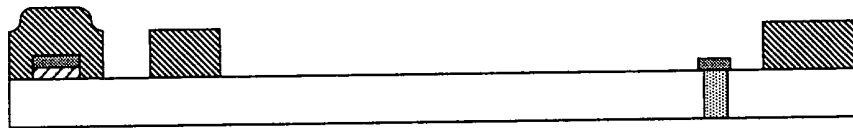
Attorney: Ted R. Rittmaster - 047711-0319

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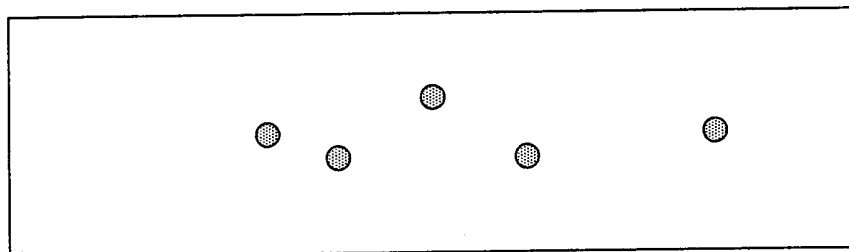


Figure 2d

HIGH RELIABILITY MULTILAYER CIRCUIT  
SUBSTRATES AND METHODS FOR THEIR  
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Attorney: Ted R. Rittmaster - 047711-0319

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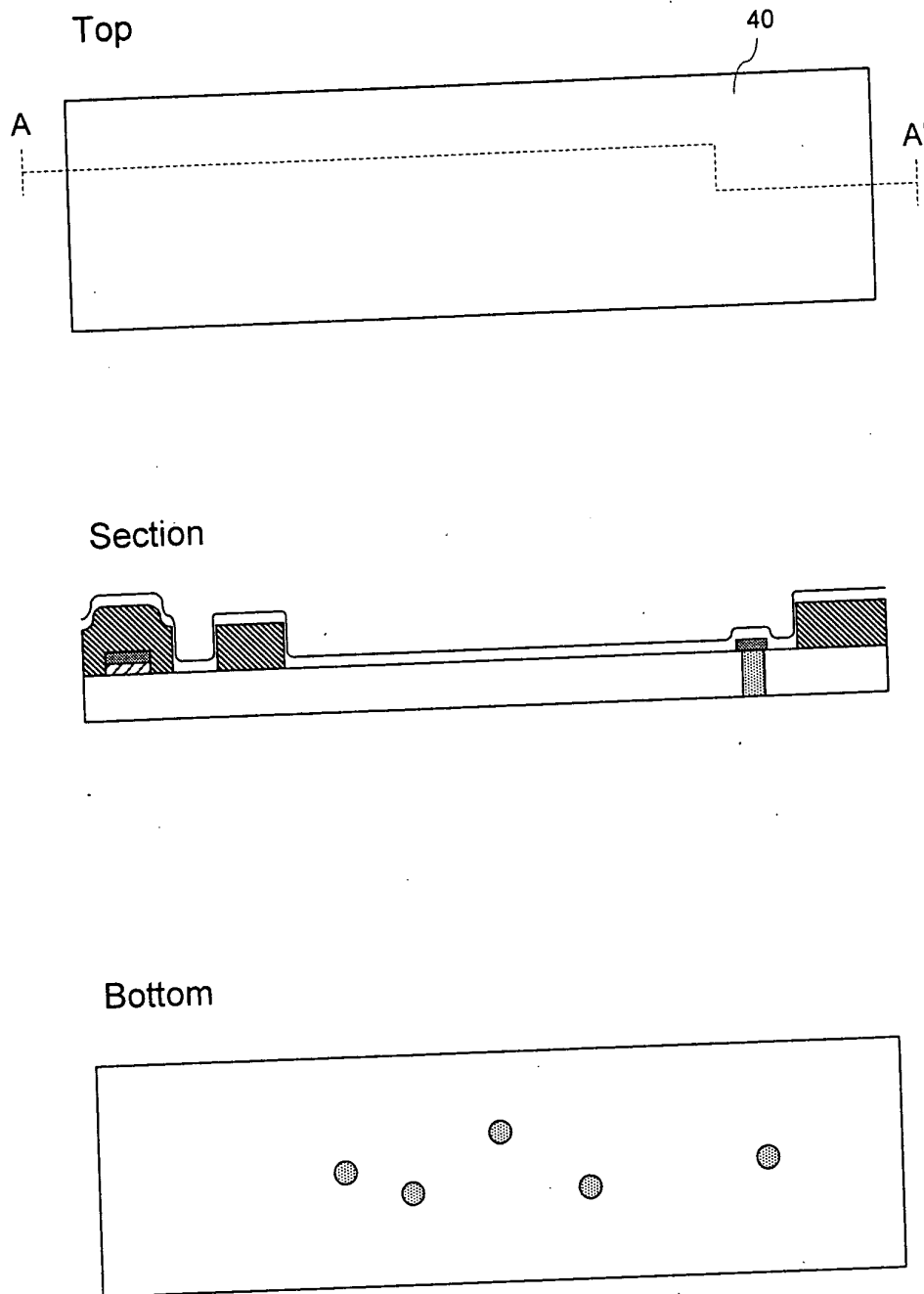


Figure 2e

HIGH RELIABILITY MULTILAYER CIRCUIT  
SUBSTRATES AND METHODS FOR THEIR  
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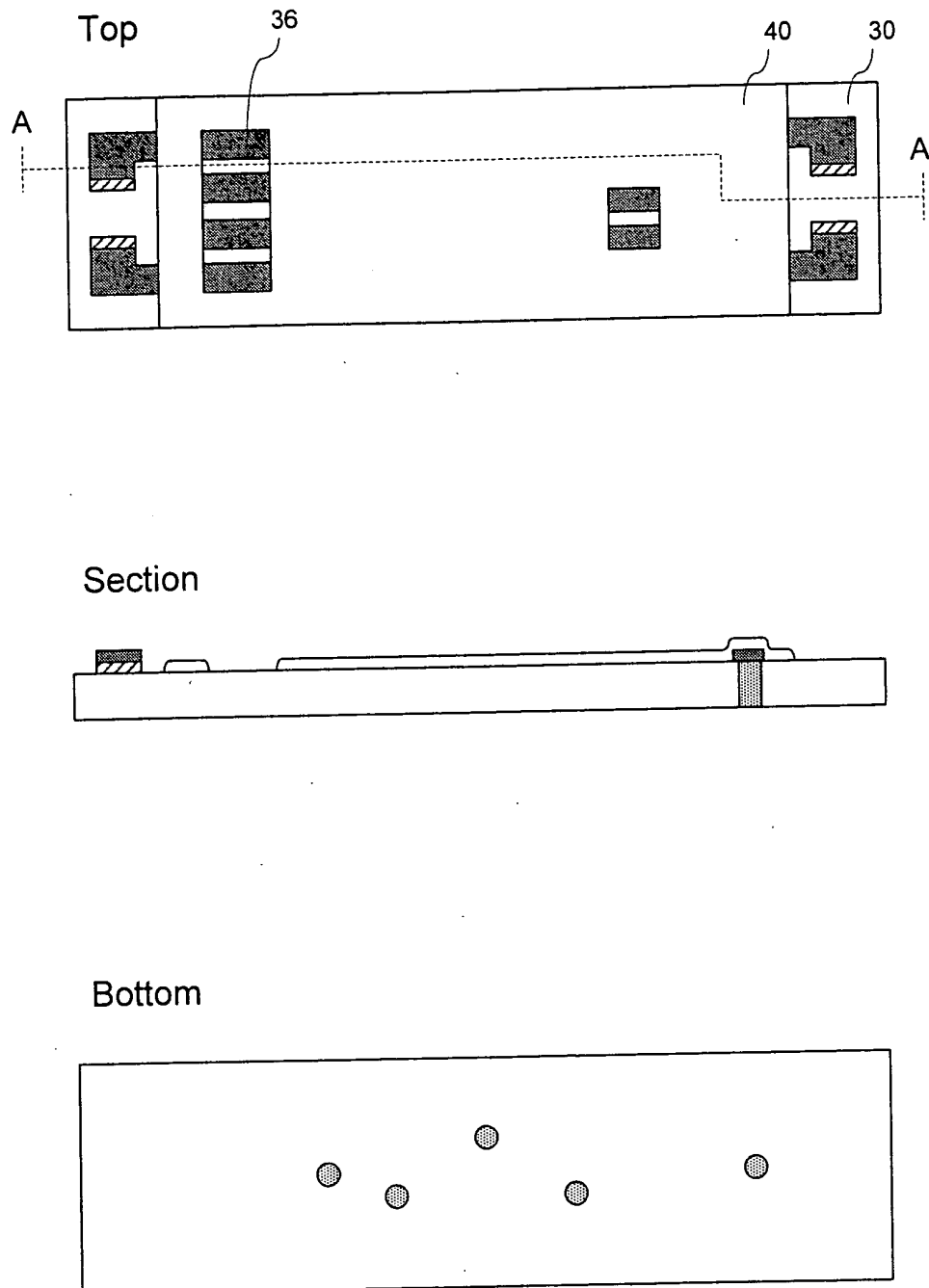


Figure 2f



HIGH RELIABILITY MULTILAYER CIRCUIT  
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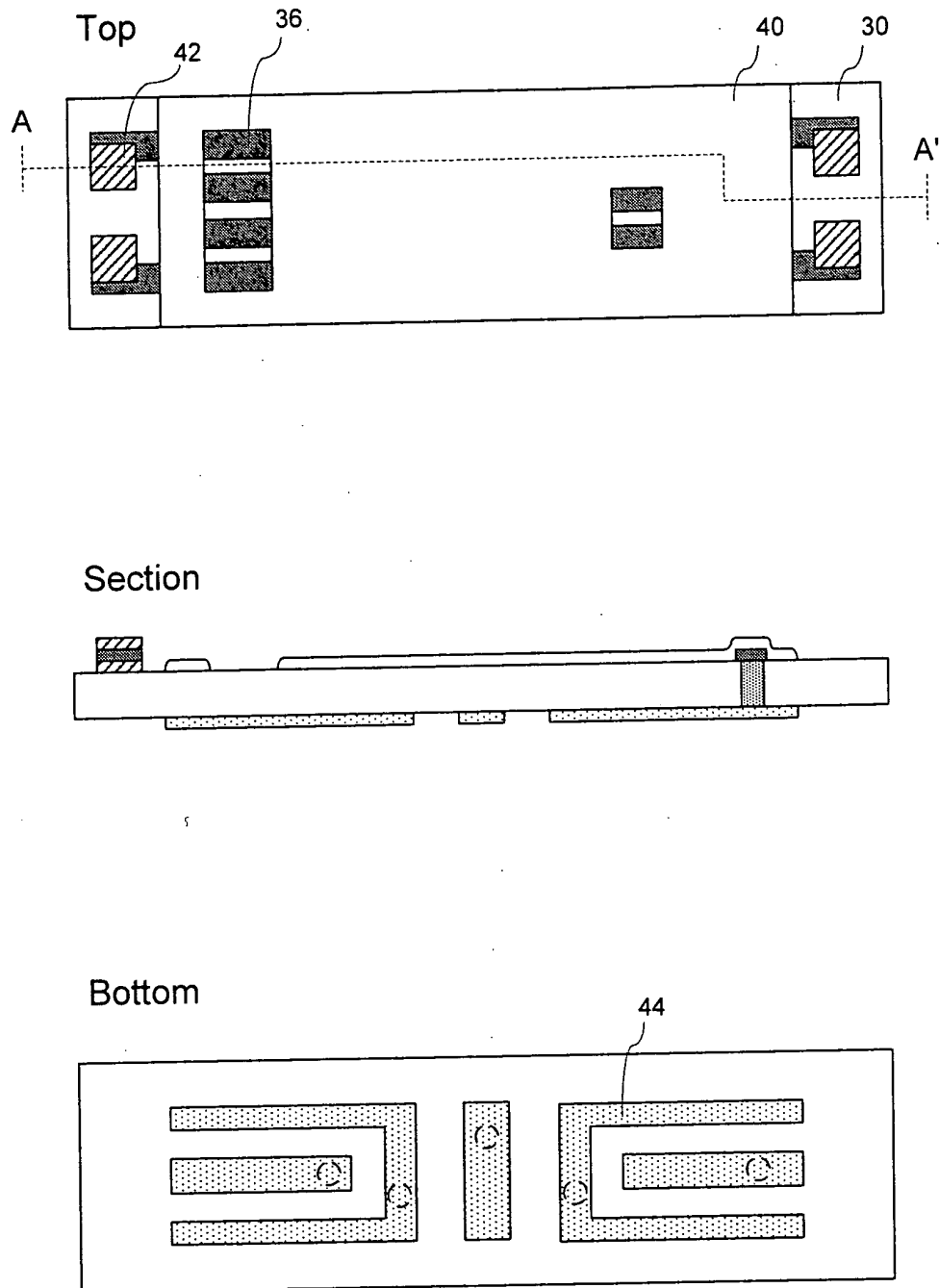
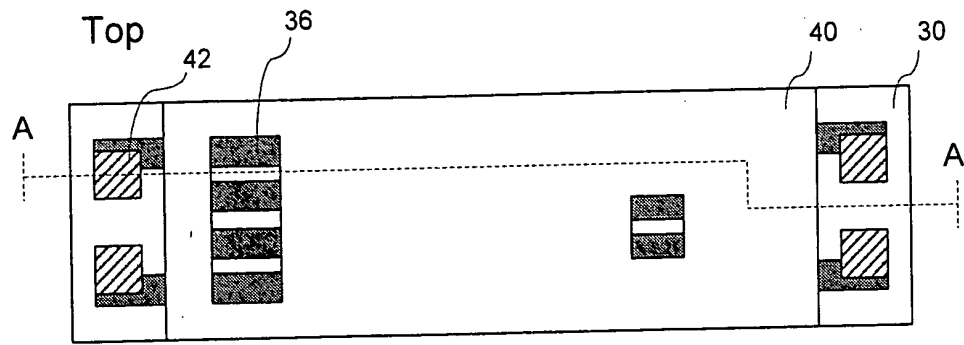


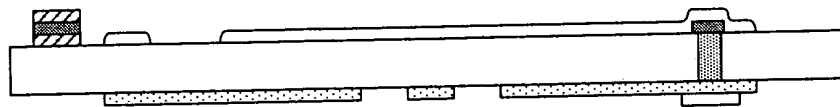
Figure 2g

HIGH RELIABILITY MULTILAYER CIRCUIT  
SUBSTRATES AND METHODS FOR THEIR  
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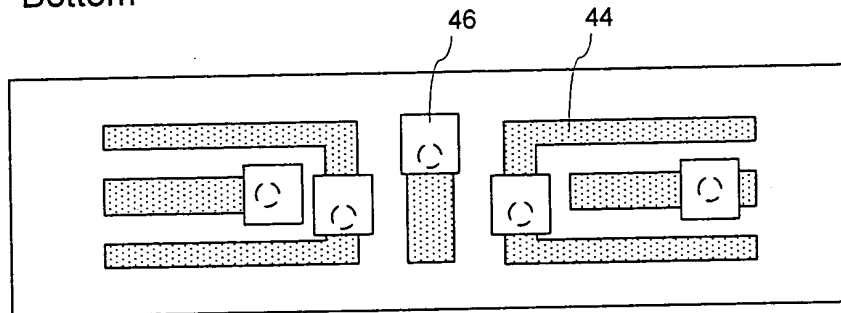


Figure 2h

HIGH RELIABILITY MULTILAYER CIRCUIT  
SUBSTRATES AND METHODS FOR THEIR  
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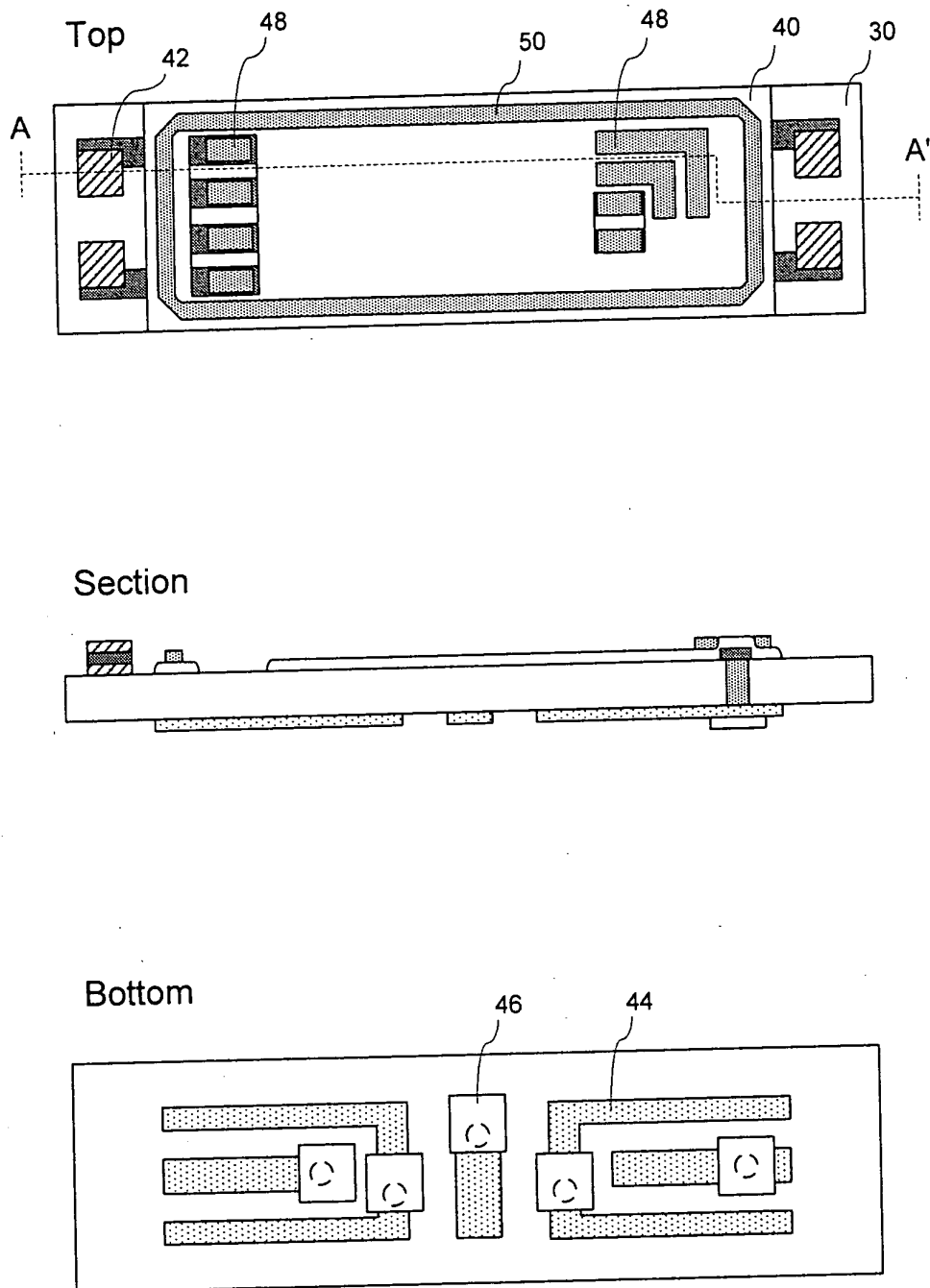


Figure 2i

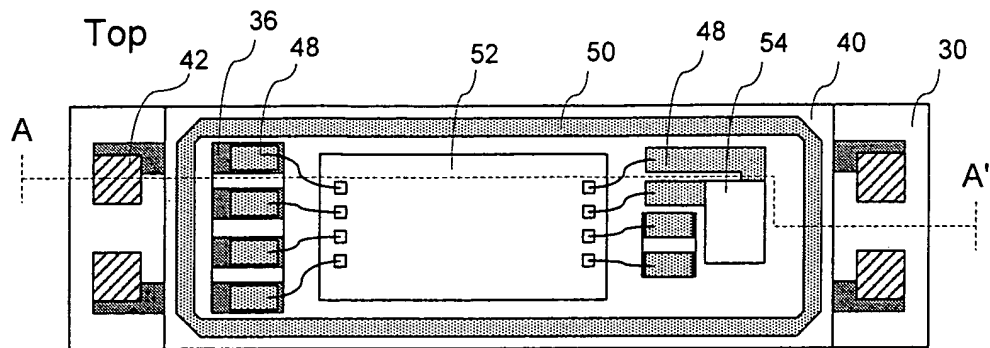
HIGH RELIABILITY MULTILAYER CIRCUIT  
SUBSTRATES AND METHODS FOR THEIR  
FORMATION

Inventors: Rajiv Shah et al.

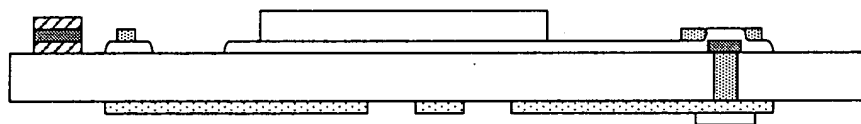
Attorney: Ted R. Rittmaster - 047711-0319

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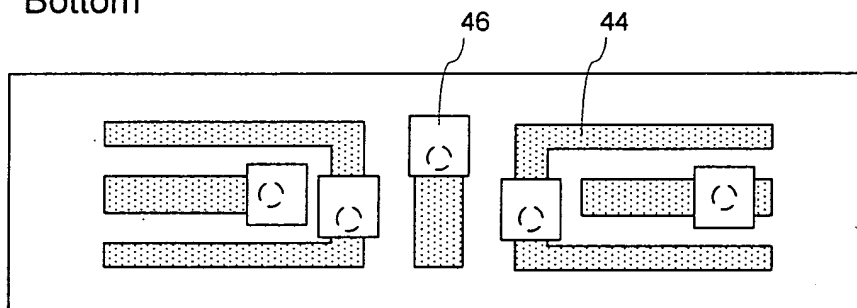


Figure 2j

HIGH RELIABILITY MULTILAYER CIRCUIT  
SUBSTRATES AND METHODS FOR THEIR  
FORMATION

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Attorney: Ted R. Rittmaster - 047711-0319

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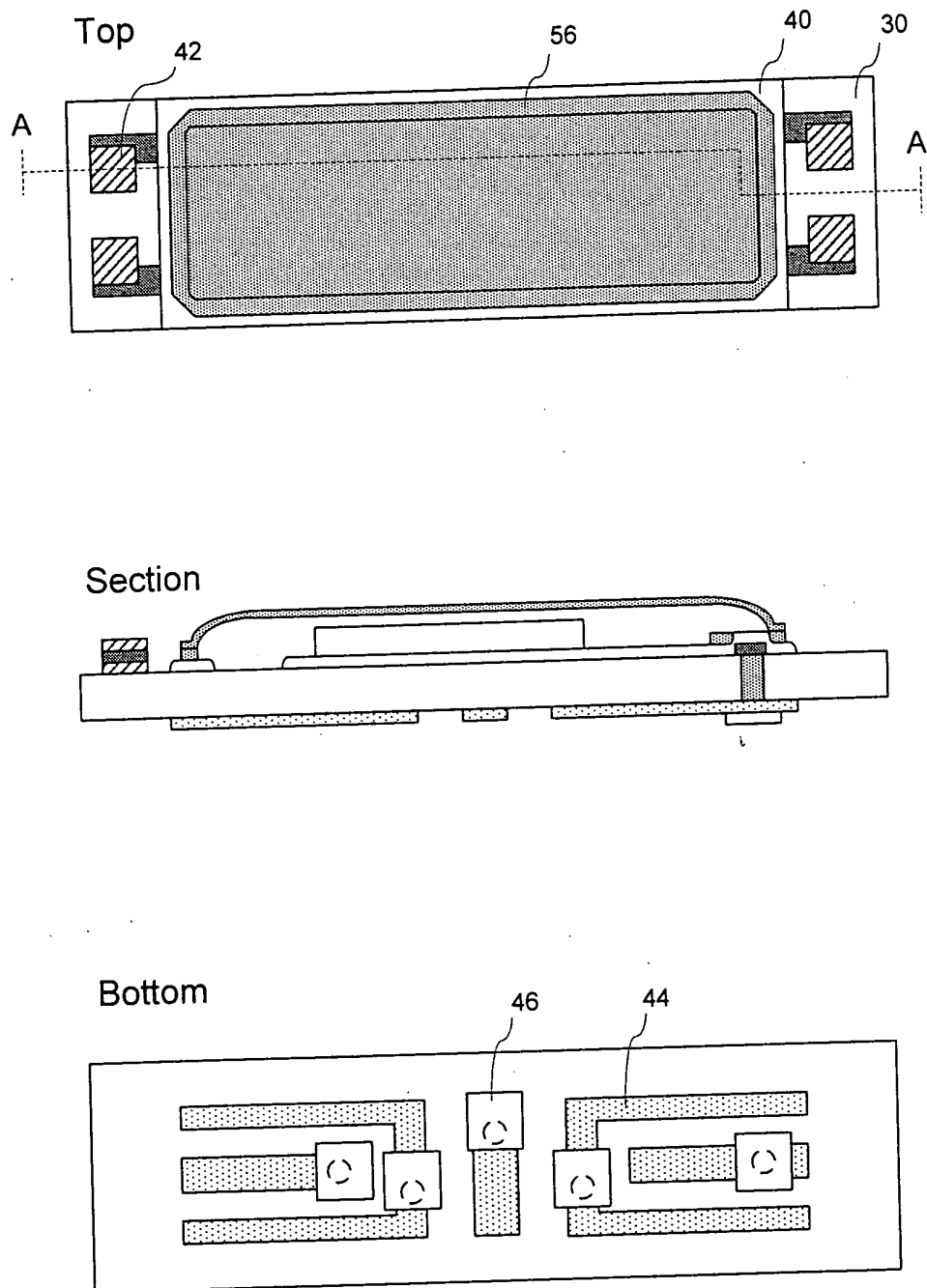
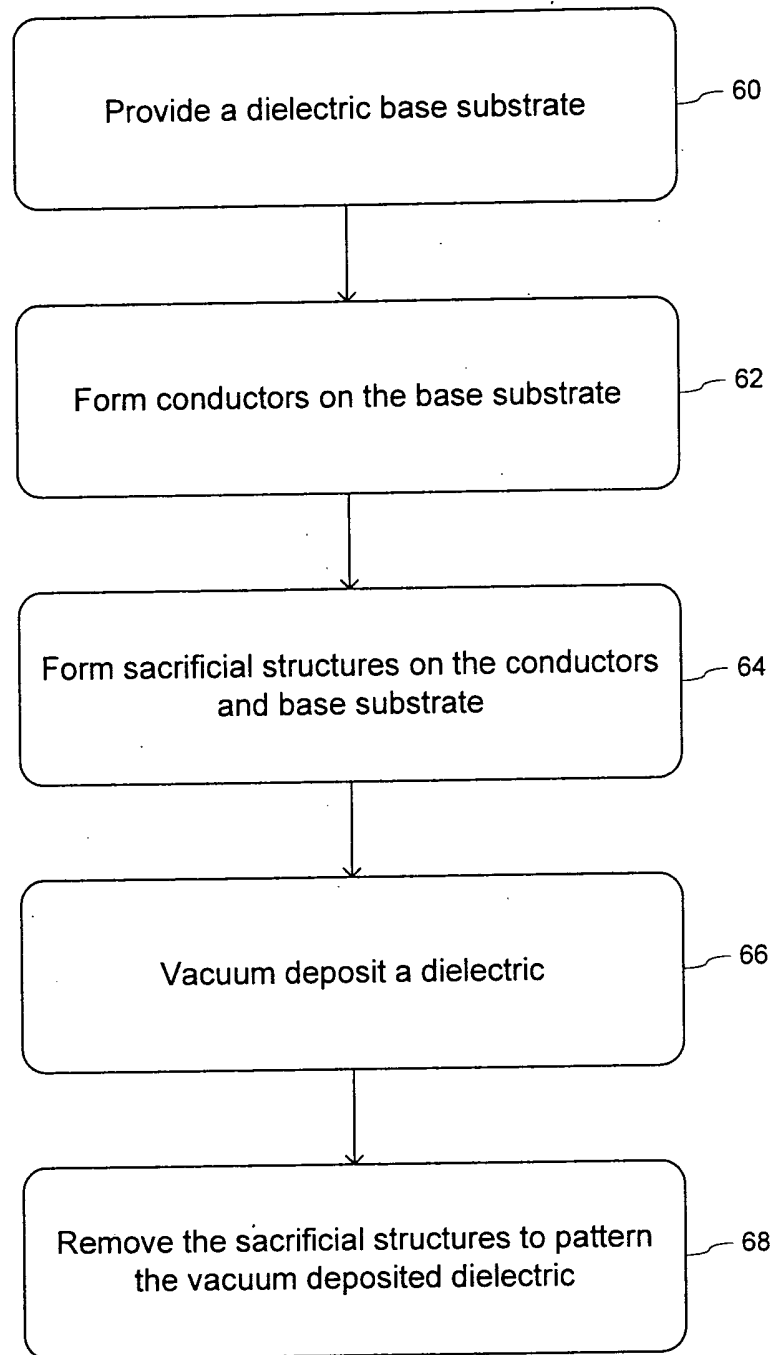


Figure 2k



**Figure 3**